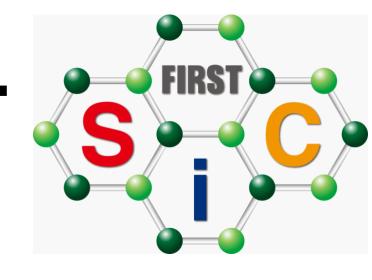


Compact Modeling of the Punch-Through Effect in SiC-IGBT for 6.6kV Switching Operation with Improved Performance





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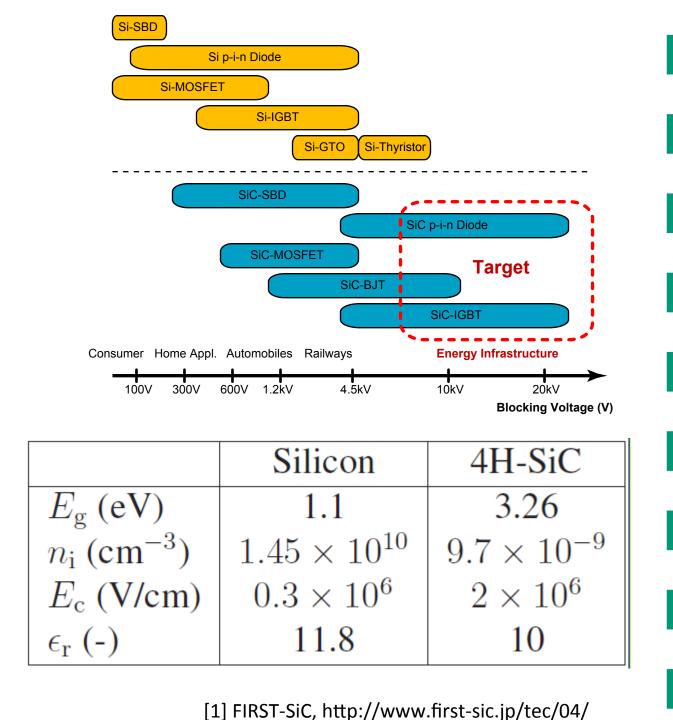


Motivation

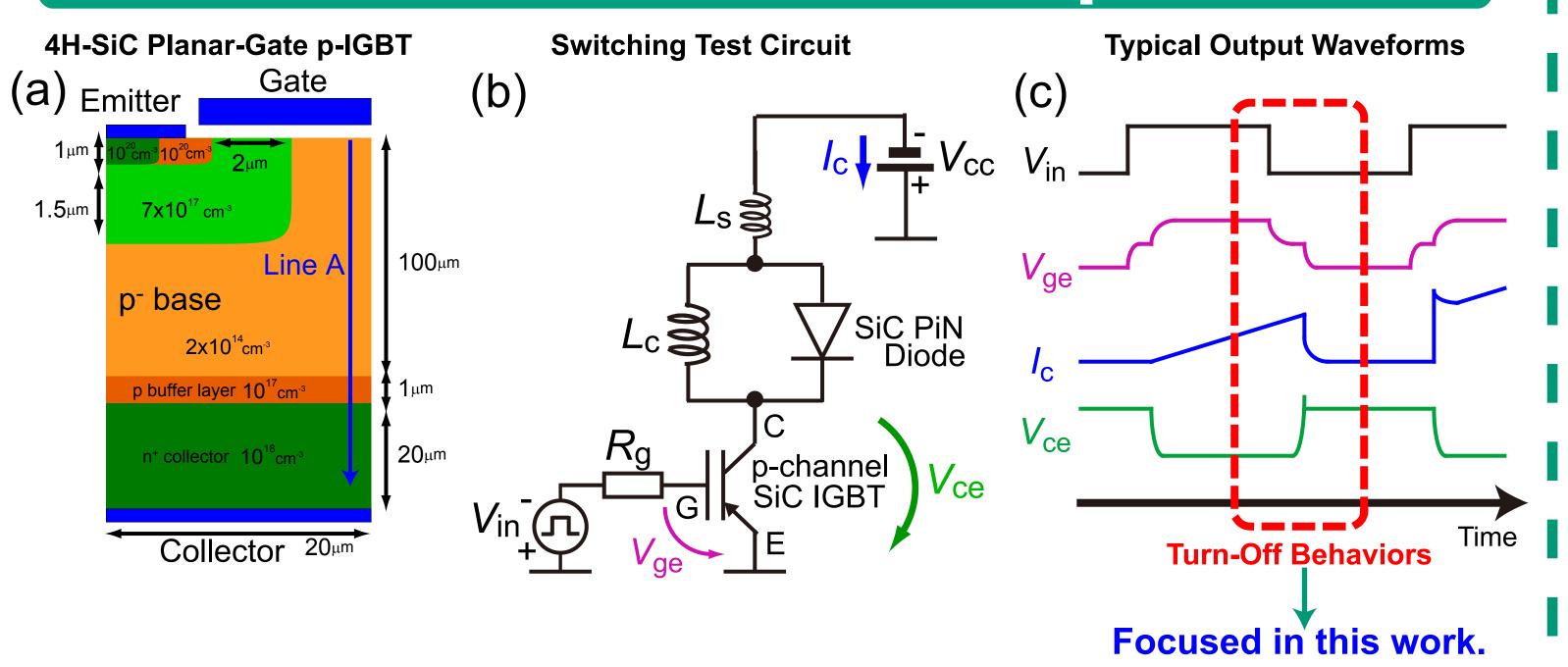
- For over 5kV & 100A/cm² operations at a few hundred Hz switching frequency, SiC IGBTs have the lowest on-state voltage among state-of-the-art high-voltage power semiconductor devices such as silicon light-triggered thyristors [1].
- Accurate and stable compact model of SiC IGBTs for circuit simulation is required for circuit designers to efficiently design/optimize circuitry of power converters.

Benefits from the good compact model

- 1. Higher conversion efficiency
- 2. Reduction of cost
- 3. Less turn-around time

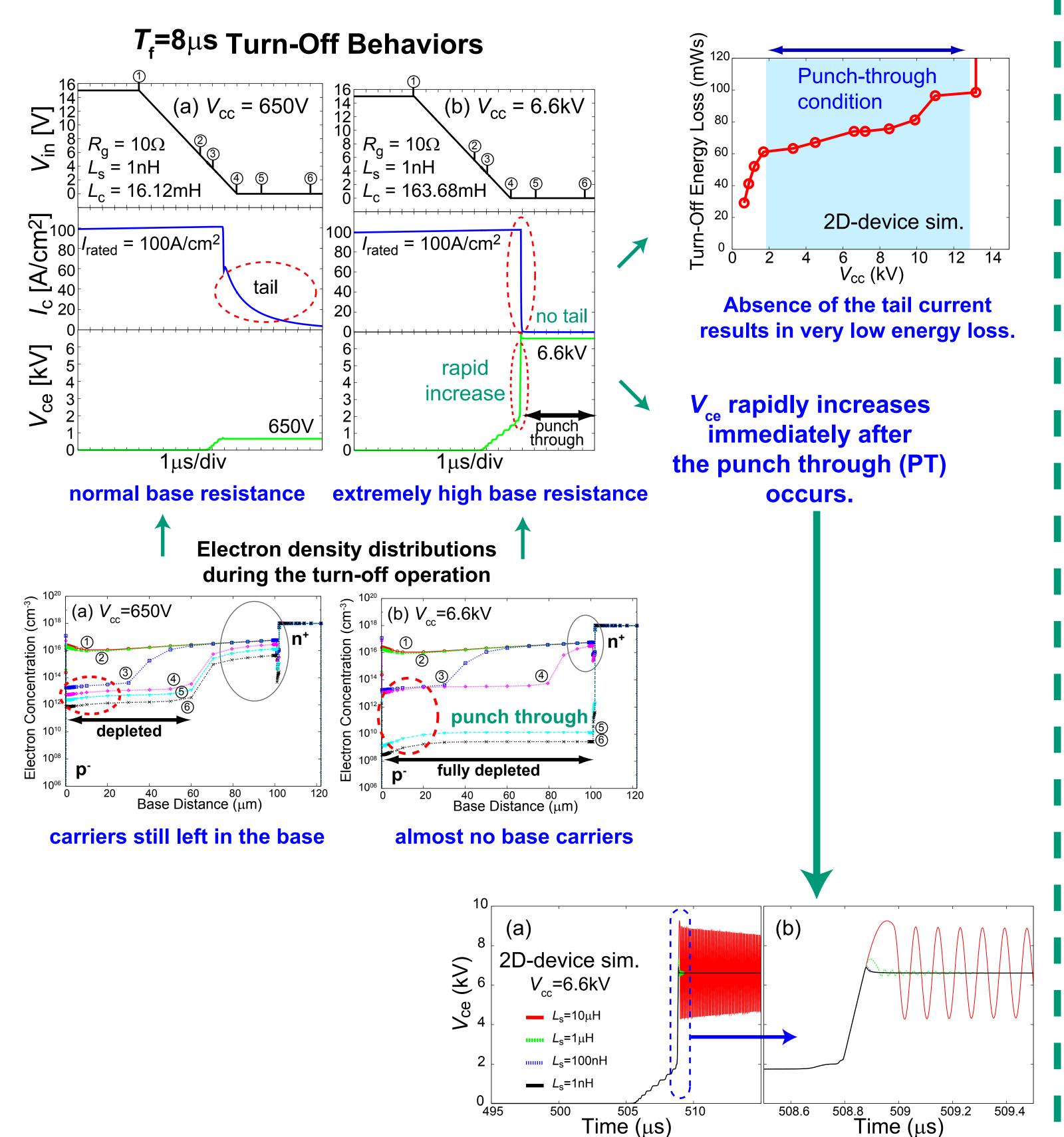


Simulation Setup



Investigation with 2D-Device Simulation

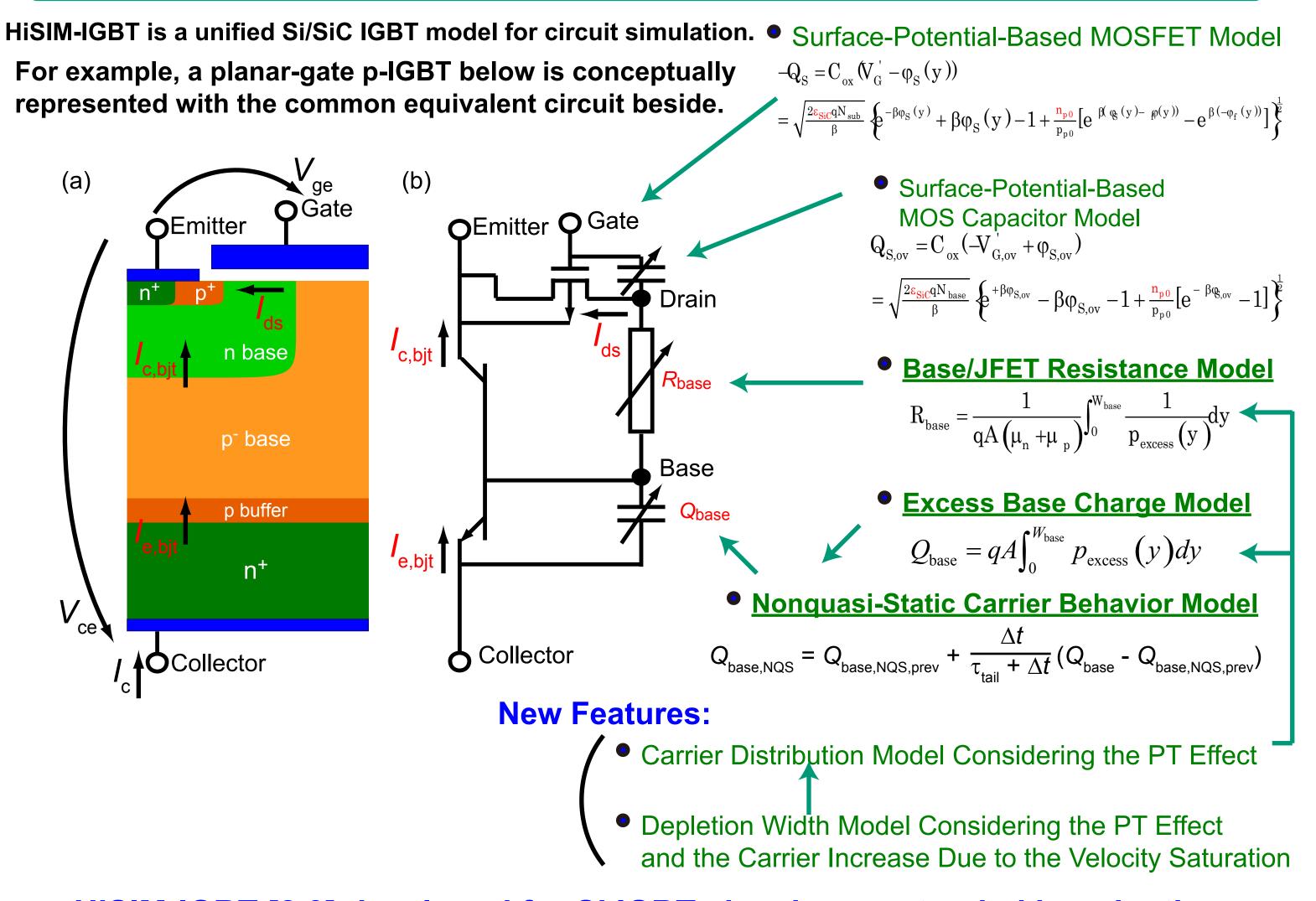
2D-device simulation is performed using ATLAS by Silvaco.



Rapid increase of V_{ce} causes a large voltage overshoot which can trigger a ringing phenomenon if a parasitic stray inductance L_{s} is relatively large.

To exploit the advantage in the turn-off energy loss while at the same time avoid the ringing, the punch-through (PT) effect must be modeled accurately.

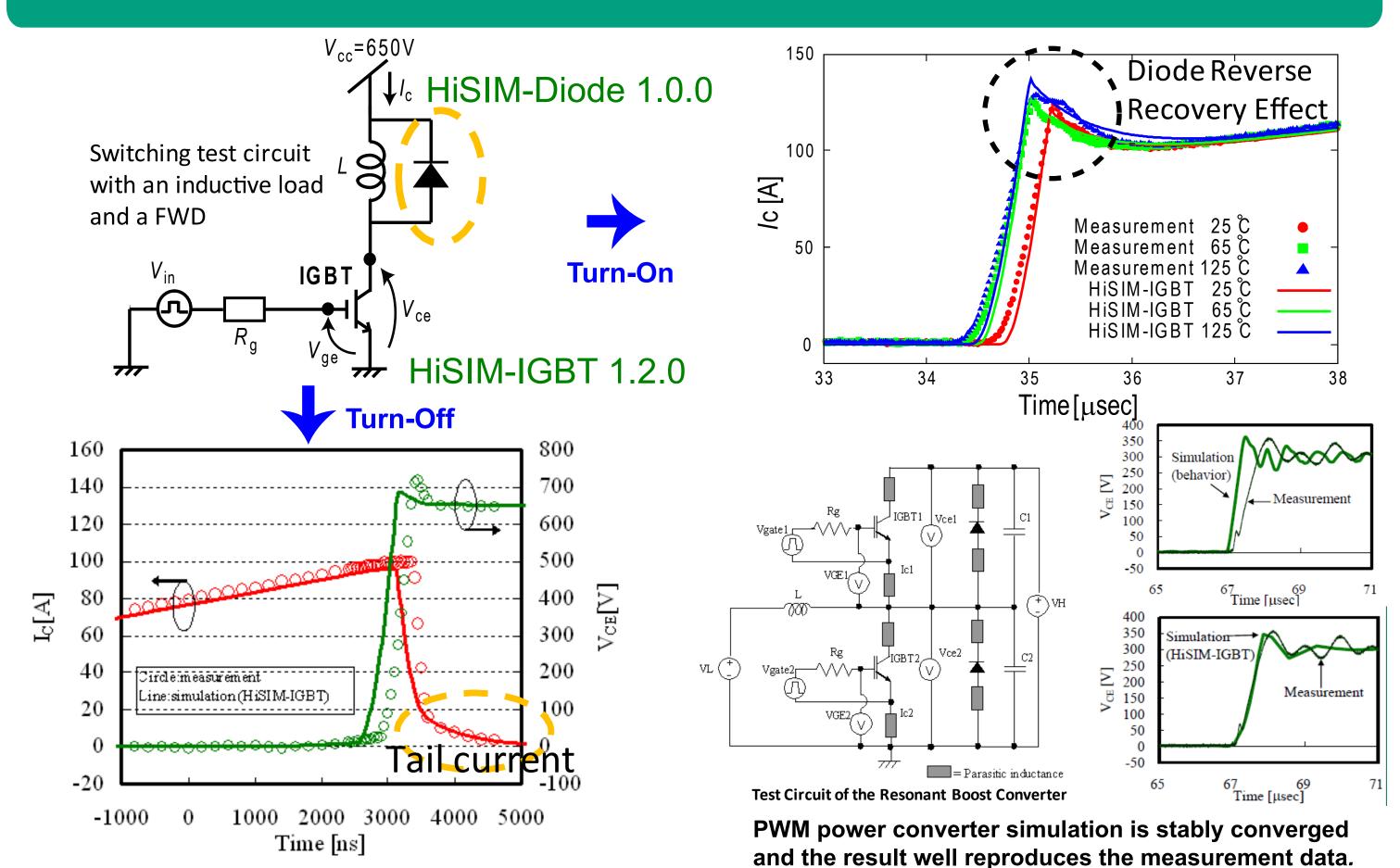
Compact Model HiSIM-IGBT



HiSIM-IGBT [2,3] developed for Si IGBTs has been extended by adapting material parameters to 4H-SiC and by including new features for the PT effect.

[2] M. Hirose, K. Hamada, K. Shizuku, M. Miyake, M. Miura-Mattausch, H. J. Mattausch, and U. Feldmann, "Development of the HiSIM-IGBT Model for EV/HV Electric Circuit Simulation," in Proc. the 1st Int'l Electric Vehicle Tech. Conf. (EVTeC), Yokohama, May 2011.
[3] M. Miyake, M. Ueno, J. Nakashima, H. Masuoka, U. Feldmann, H. J. Mattausch, M. Miura-Mattausch, T. Ogawa, T. Ueta, "Temperature Dependence of Switching Performance in IGBT Circuits and its Compact Modeling," in Proc. ISPSD, pp. 148-151, San Diego, May 2011.

Achievements of HiSIM-IGBT for Silicon Data



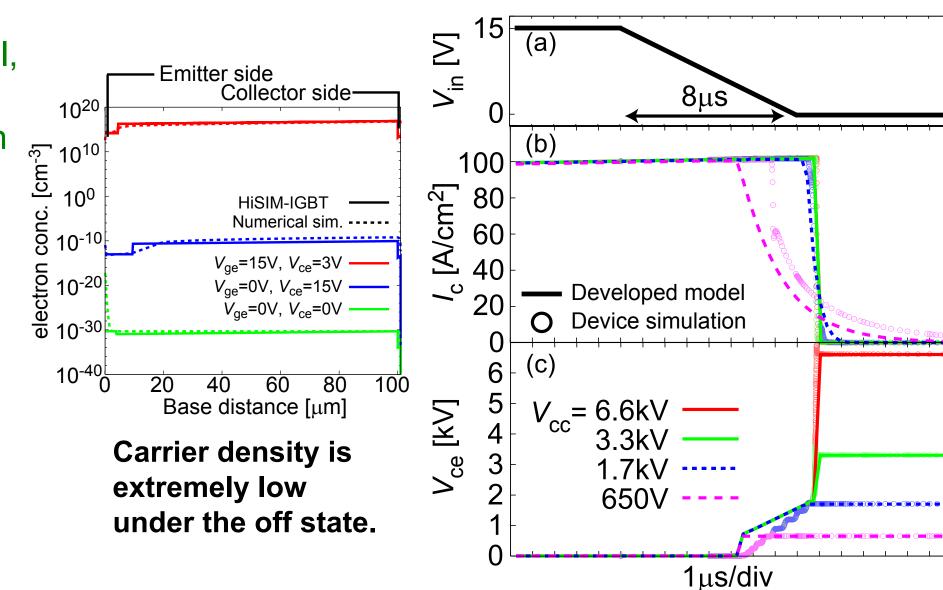
HiSIM-IGBT is verified to reproduce accurately the dynamic characteristics of Si IGBT circuits.

HiSIM-IGBT Extension and Verification for SiC

 To extend the HiSIM-IGBT model, the material parameters of SiC are included through the Poisson equation of the MOSFET part and through the excess carrier density in the base region.

 The punch though effect is included in the modeling of the base region.

 The model is implemented and verified in Spice3f5.



Absence of the tail current and the rapid increase of $V_{\rm ce}$ are reproduced correctly by the developed model.

Conclusions

- HiSIM-IGBT is extended to model the SiC IGBT device.
- Correct turn-off characteristics of the 4H-SiC IGBT for different supply voltages are verified, which is important for accurate calculation of energy loss and the ringing phenomena.

Acknowledgment

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